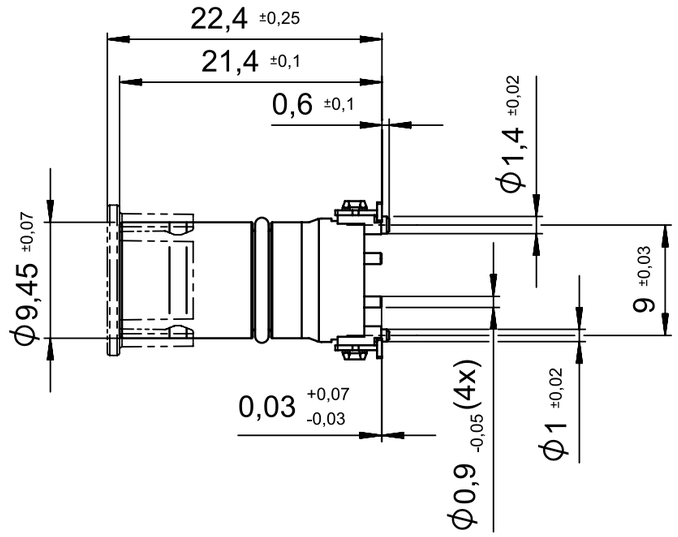
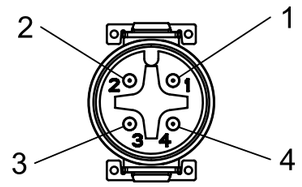
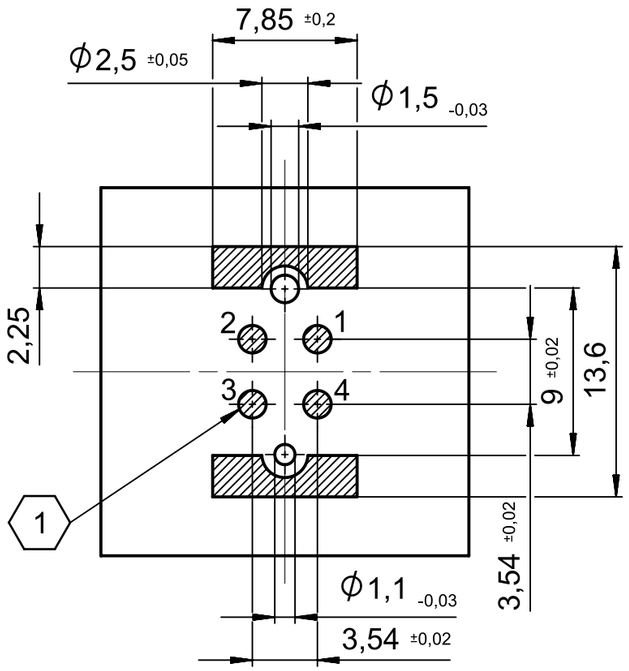




plug face male



PCB-layout (advice)



3:1

Coplanarity of all contacts and anchor plate | 0.1

Recommended solder paste thickness 150µm

(1) Further information on soldering process and recommended layout, see brochure "Connectors for SMT production"

- EN ISO 291 23/50

DIN A3	document-no. / ri: 102983917 / 00	article-no. / ri: 1411996 / 09	scale: 2:1
PHOENIX CONTACT	date: 2025-10-29	document-type: TECDOC 2D-Productdrawing	- Simplified representation - Linear dimensions (mm)
	page 1 of 1	description: SACC-CIP-M12MS-4P SMD R32	

Weitergabe sowie Vervielfältigung dieses Dokuments, Verwertung und Mitteilung seines Inhalts sind verboten, soweit nicht ausdrücklich gestattet. Zuwiderhandlungen verpflichten zu Schadenersatz. Alle Rechte für den Fall der Patent-, Gebrauchsmuster- oder Designeintragung vorbehalten. Bauartbedingtes Spiel ist in den Toleranzangaben nicht berücksichtigt.

Transfer or duplication of this document as well as the utilisation or communication of its content are not permitted unless express consent is granted. Violations give rise to claims for damages. All rights reserved in case of patent, utility model or design patent registrations. Toerance specifications do not include clearances inherit in the design.